TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ($L^2-\pi$ -MOSIII)

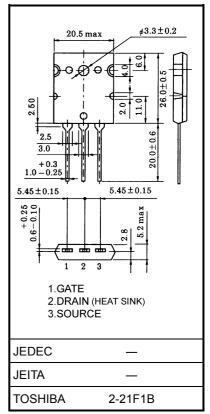
2SK1382

Relay Drive, Motor Drive and DC–DC Converter Applications

- 4 V gate drive
- Low drain-source ON resistance $: R_{DS} (ON) = 15 m\Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 47 \text{ S} (\text{typ.})$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 100 \ V)$
- Enhancement-mode : $V_{th} = 0.8 \sim 2.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Maximum Ratings (Ta = 25°C)

| Characteristics | | Symbol | Rating | Unit | |
|--|----------------|------------------|---------|------|--|
| Drain-source voltage | | V _{DSS} | 100 | V | |
| Drain-gate voltage (R _{GS} = 20 kΩ) | | V _{DGR} | 100 | V | |
| Gate-source voltage | | V _{GSS} | ±20 | V | |
| Drain current | DC (Note 1) | ۱ _D | 60 | А | |
| | Pulse (Note 1) | I _{DP} | 240 | 4 | |
| Drain power dissipation (Tc = 25°C) | | PD | 200 | W | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature range | | T _{stg} | -55~150 | °C | |



Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|--|------------------------|-------|--------|
| Thermal resistance, channel to case | R _{th (ch−c)} | 0.625 | °C / W |
| Thermal resistance, channel to ambient | R _{th (ch−a)} | 35.7 | °C / W |

Note 1: Please use devices on condition that the channel temperature is below 150°C.

This transistor is an electrostatic sensitive device. Please handle with caution. Weight: 9.75 g (typ.)

Unit: mm

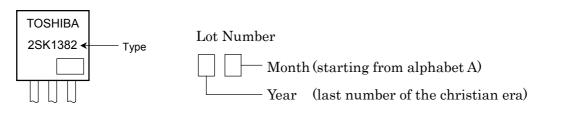
Electrical Characteristics (Ta = 25°C)

| Charao | cteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|-----------------|----------------------|--|-----|------|------|------|
| Gate leakage cu | ırrent | I _{GSS} | V _{GS} = ±20 V, V _{DS} = 0 V | | | ±100 | nA |
| Drain cut-off cu | rrent | IDSS | V _{DS} = 100 V, V _{GS} = 0 V | | | 100 | μA |
| Drain-source br | eakdown voltage | V (BR) DSS | I _D = 10 mA, V _{GS} = 0 V | 100 | _ | _ | V |
| Gate threshold | voltage | V _{th} | V _{DS} = 10 V, I _D = 1 mA | 0.8 | | 2.0 | V |
| Drain-source ON resistance | | R _{DS (ON)} | V _{GS} = 4 V, I _D = 30 A | | 20 | 29 | mΩ |
| | | | V _{GS} = 10 V, I _D = 30 A | | 15 | 20 | |
| Forward transfe | r admittance | Y _{fs} | V _{DS} = 10 V, I _D = 30 A | 30 | 47 | _ | S |
| Input capacitance | ce | C _{iss} | | _ | 7000 | _ | |
| Reverse transfer capacitance | | C _{rss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | _ | 400 | _ | pF |
| Output capacitance | | C _{oss} | | _ | 2700 | _ | |
| Switching time | Rise time | tr | $v_{GS} \stackrel{10V}{}_{0V} \int I_{D} = 30A$ $V_{OUT} V_{OUT}$ $R_{L} = 1.6\Omega$ | _ | 16 | _ | |
| | Turn-on time | t _{on} | | _ | 55 | _ | - ns |
| | Fall time | t _f | | _ | 80 | _ | |
| | Turn-off time | t _{off} | V_{DD} \doteqdot 50V Duty \leq 1%, t _w =10 μ s | _ | 280 | _ | |
| Total gate charge (Gate-source plus gate-drain) | | Qg | | _ | 176 | _ | |
| Gate-source charge | | Q _{gs} | V _{DD} ≈ 80 V, V _{GS} = 10 V, I _D = 60 A | | 132 | _ | nC |
| Gate-drain ("miller") charge | | Q _{gd} |] | _ | 44 | _ | |

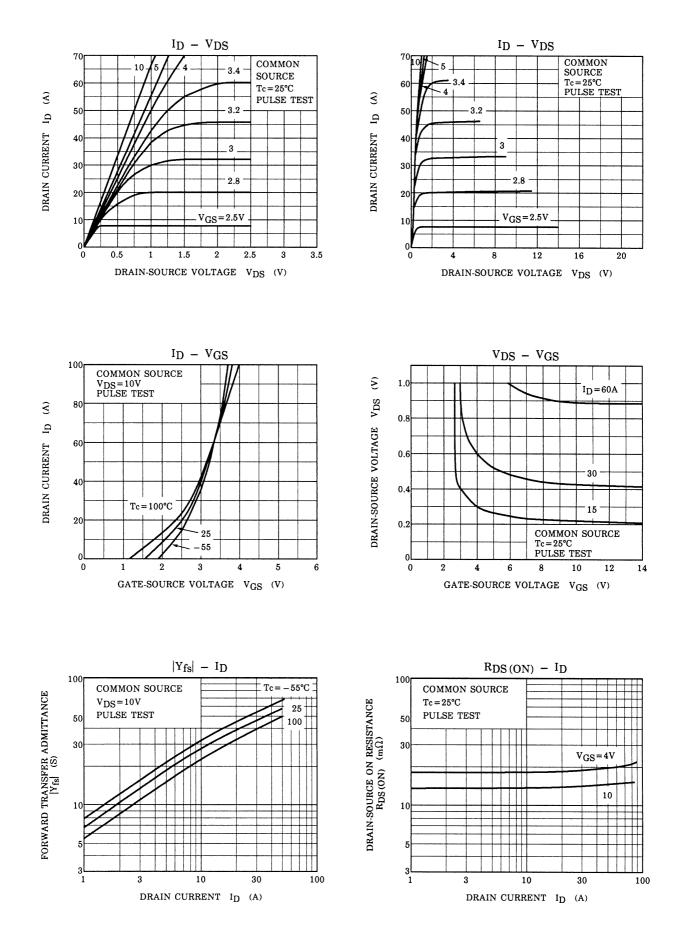
Source–Drain Ratings and Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--|------------------|---|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I _{DR} | — | _ | _ | 60 | А |
| Pulse drain reverse current (Note 1) | I _{DRP} | — | _ | _ | 240 | A |
| Forward voltage (diode) | V _{DSF} | I _{DR} = 60 A, V _{GS} = 0 V | _ | _ | -1.6 | V |
| Reverse recovery time | t _{rr} | I _{DR} = 60 A, V _{GS} = 0 V | _ | 300 | — | ns |
| Reverse recovered charge | Q _{rr} | dI _{DR} / dt = 50 Å / µs | _ | 0.75 | — | μC |

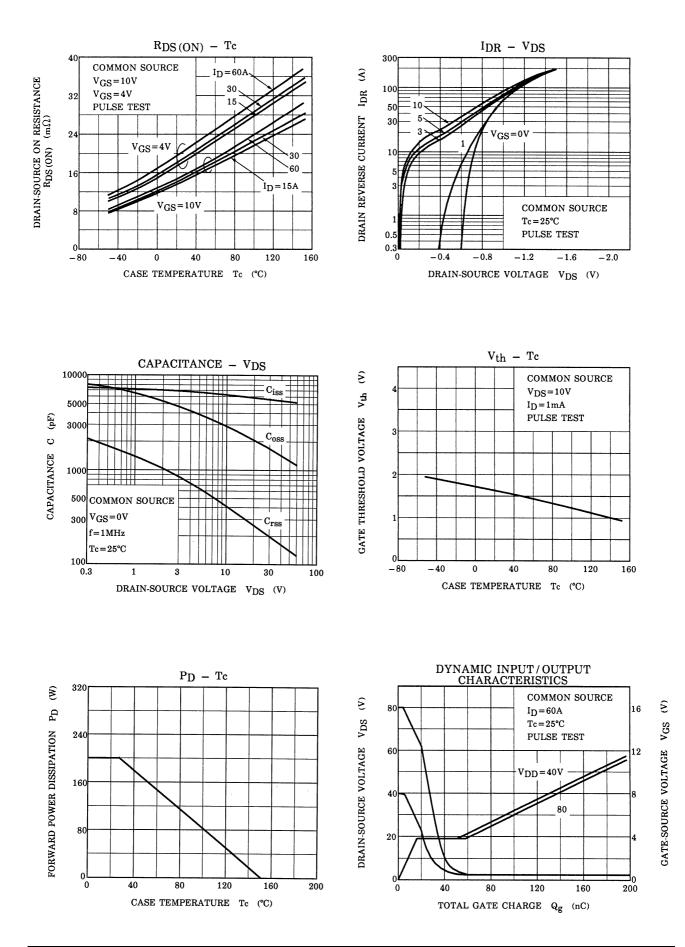
Marking

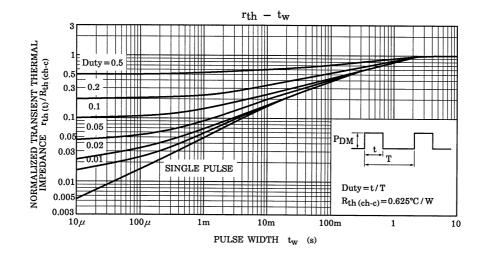


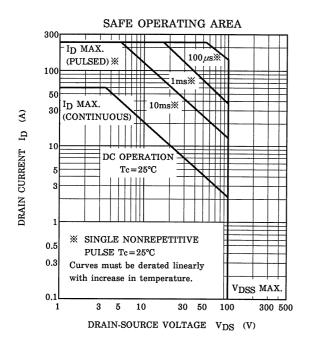
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